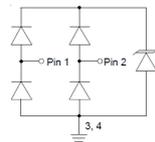


Features

- 100W(8/20 μ s) Peak Pulse Power
- Ultra Low Capacitance ESD Protection
- Flow Through DFN1.6x1.0-6L Package
- RoHS Compliant
- Matte Tin Lead finish (Pb-Free)
- Protect Two High Speed Data Lines
- Meet IEC61000-4-2 Level 4:
 - Contact Discharge > 12kV
 - Air Discharge > 17kV

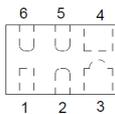
Circuit Diagram



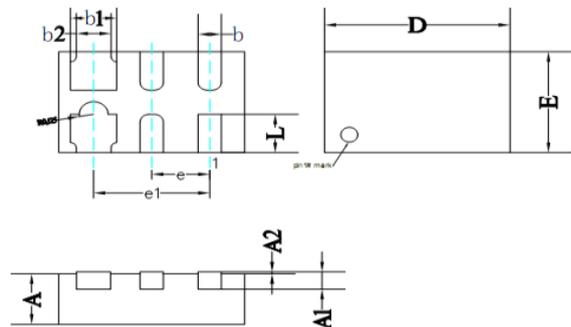
Applications

- PCI Express
- MDDI Ports
- eSATA Interfaces
- Display Port Interface
- Digital Visual Interface (DVI)
- High Definition Multi-Media Interface (HDMI)

PIN Diagram



DFN1.6X1.0-6L



ALL DIMENSIONS IN MM

	MIN	NOM	MAX
D	1.55	1.60	1.65
E	0.95	1.00	1.05
L	0.33	0.38	0.43
b	0.15	0.20	0.25
b1	0.35	0.40	0.45
b2	0.25	0.30	0.35
e	0.50BSC		
e1	1.00BSC		
A	0.45	0.50	0.55
A1	0.15REF		
A2	0.00	-	0.05

Dimensions in inches and (millimeters)

Maximum Ratings (Ta = 25°C)

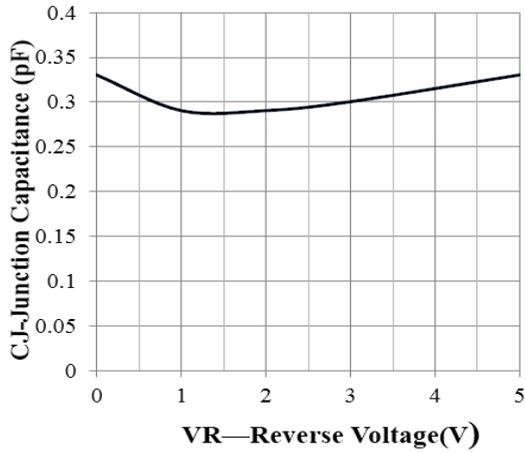
Symbol	Parameter	Value	Unit
PPK	Peak Pulse Power	100	W
IPP	Peak Pulse Current	4.5	A
VESD (Contact)	Contact ESD Voltage per IEC61000-4-2	12	kV
VESD (Air)	Air ESD Voltage per IEC61000-4-2	17	kV
TJ	Junction Temperature	-55 to +125	°C
TSTG	Storage Temperature	-55 to +150	°C

RCLAMP0522P

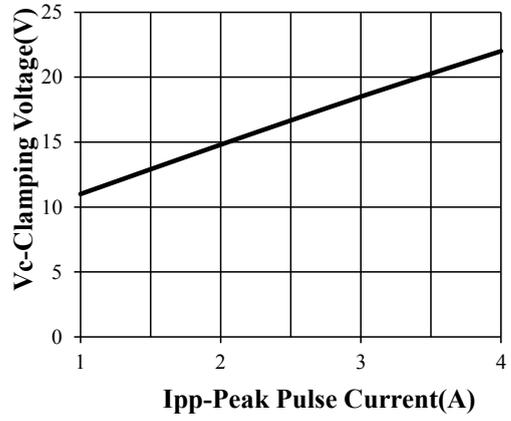
Electrical Characteristics (Ta = 25°C)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
VRWM	Reverse Working Peak Voltage				5	V
VBR	Reverse Breakdown Voltage	IT = 1mA	6			V
IR	Reverse Leakage Current	VRWM = 5V			1	μA
VC	Clamping Voltage	IPP = 4 . 5 A (8/20μs)			25	V
CJ	Capacitance	VR = 0V, f = 1MHz Between I/O pins			0.5	pF
CJ	Capacitance	VR = 0V, f = 1MHz Any I/O pin to ground			0.9	pF

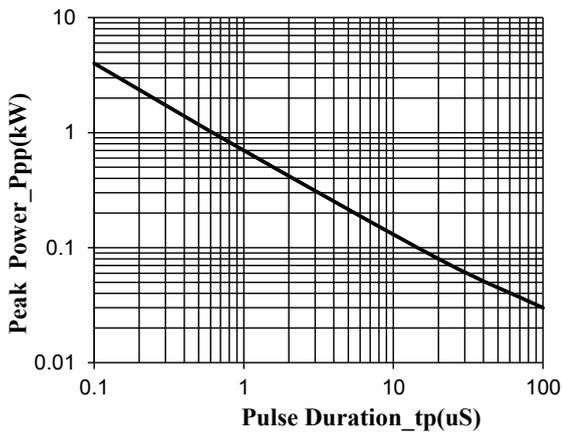
RATING AND CHARACTERISTIC CURVES (RCLAMP0522P)



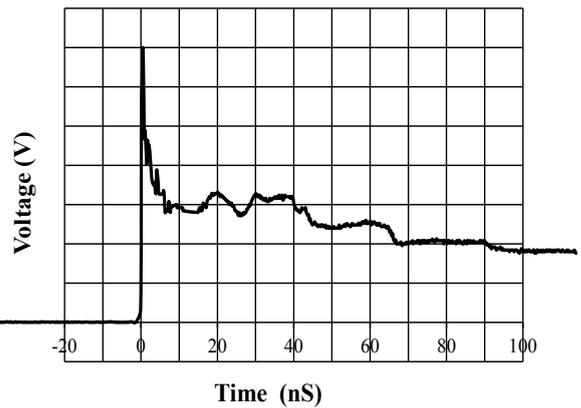
Junction Capacitance vs. Reverse Voltage



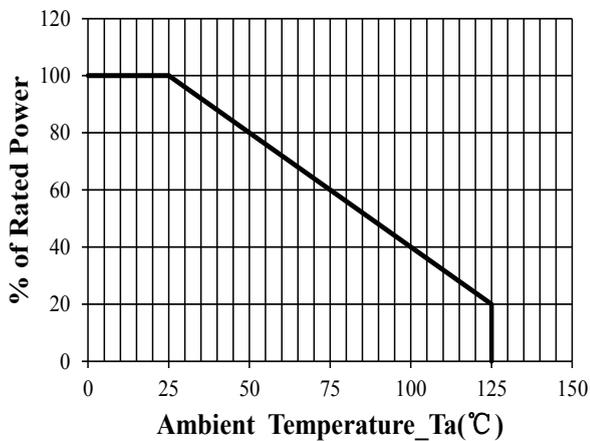
Clamping Voltage vs. Peak Pulse Current



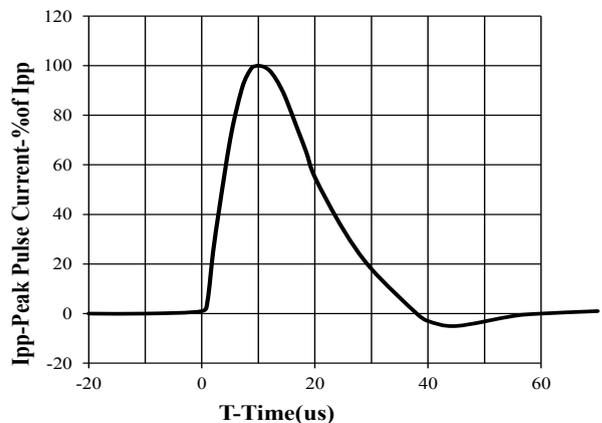
Peak Pulse Power vs. Pulse Time



IEC61000-4-2 Pulse Waveform



Power Derating Curve



8 X 20us Pulse Waveform